シリコン表面パッシベーションの実時間観察 ~欠陥とバンドオフセットの効果~

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Abstract

- Surface passivation of crystalline silicon (c-Si) is studied during • growth of a hydrogenated amorphous silicon (a-Si:H) and epitaxial silicon (epi-Si) passivation layer at subnanometer to nanometer scale.
- The passivation is improved by the growth of an a-Si:H layer, where a large band offset is formed at the a-Si:H/c-Si interface.
- The passivation is deteriorated with the growth of an epi-Si, because the band offset is not formed at the interface, and plasma-induced

Exp. setup: in-situ real-time photocurrent measurement



- Silicon on insulator (SOI) is used as a sample for the photocurrent measurement.
- SOI is illuminated with a semiconductor laser (520nm, 1mW).
- The **photocurrent** is measured during plasma proicessing and subsequent postannealing.

defects are created in c-Si.

SHJ solar cell, interface defects and carrier lifetime



• In silicon heterojunction (SHJ) solar cells, a-Si:H layer plays important roles in surface passivation & carrier selection.



• The carrier lifetime, i.e., a measure for the surface passivation, varies throughout the fabrication process of SHJ solar cells.





- In experiments, **the treatment time (\Deltat)** and temperature (T) are varied.

S. Nunomura et al., Appl. Phys. Express. 12, 051006 (2019).

Experimental results

Time evolution of photocurrents



Time evolutions of photocurrents, I_{p} , in SOI during growth and consecutive annealing at (a) D = 0and (c) D = 20. For comparison, the time evolution of I_p for H_2 plasma treatments is shown in (d).

I_p initially exhibits a decreasing tendency for a series of growth of an ultrathin, and then it exhibits an increasing tendency for growth of a relatively-thick layer.

The decreasing tendency reflects the deterioration of the passivation.



- Cross-sectional TEM images of passivation layers grown over SOI at different hydrogen (H₂)-dilution of (a) D = 0, (b) D = 5, and (c) D = 20.
- (a) An a-Si:H layer is grown over the SOI. (b) An epi-Si layer is initially grown ulletin a few nm, and then an a-Si:H layer is grown over the epi-Si layer. (c) An epi-Si layer is grown from the bottom to the top of the passivation layer.

S. Nunomura et al., J. Appl. Phys. 128, 033302 (2020).



=> "defect formation"

- The increasing tendency reflects the improvement of the passivation.
- => "defect annihilation"

Photocurrent & passivation / deterioration



- I_{p}/I_{p0} is reduced with d for an ultrathin layer (d < 2.5 nm), whereas it is increased with d for a thick (d > 2.5 nm).
- The reduction in I_p/I_{p0} is enhanced for a high-D case.
- The change from the decreasing to the increasing tendency of I_p/I_{p0} takes place in a range of ~2.5 nm, implying the carrier diffusion length.

S. Nunomura et al., J. Appl. Phys. 128, 033302 (2020).

Summary

The surface passivation of c-Si is experimentally studied during growth of an a-Si:H and epi-Si layer by using in-situ real-time photocurrent measurement technique.

- (a) a-Si:H / p-type c-Si and (b) i-type epi-Si / p-type c-Si.
- The recombination centers are classified into four groups, depending on the location of defects: (i) bulk Si defects, (ii) interface defects, (iii) bulk a-Si:H or epi-Si defects, and (iv) surface defects.
- In the a-Si:H/c-Si stack, the carrier recombination is dominated by the recombination centers located at the interface and in bulk Si, denoted by (ii) and (i) respectively. In the epi-Si/c-Si stack, the carrier recombination comes from not only at above two centers, but also the recombination centers located in the epi-Si bulk and surface, denoted by (iii) and (iv).
- The passivation is maximized for an a-Si:H layer growth, due to the formation of a large valence band offset and band bending near the interface between the a-Si:H layer and the SOI. The field effect plays an important role in the passivation.
- The passivation is deteriorated with an epi-Si layer growth, because the Hmediated bulk Si defects are formed. Besides, the band bending is not fully formed near the epi-Si/SOI interface.

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